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transverse to a production direction;

providing an assembly station with at least one assembly device for equipping the individual substrates with a chip unit; and

providing a connection station with at least one connecting device for connecting the chip units to an initial coil region and to a final coil region of the coils which are formed on the substrates by the wiring devices.

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REMARKS

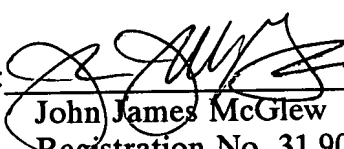
Claims 40 through 78 are in this application and are presented for consideration. Claims 1 through 39 have been cancelled.

The specification and claims have been amended in order to place this application in better form. The changes include the addition of headings and the removal of references to claim numbers.

Favorable action on the merits is respectfully requested.

Respectfully submitted
for Applicant,

By:


John James McGlew
Registration No. 31,903
McGLEW AND TUTTLE

JJM:jj/aes
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I HEREBY CERTIFY THAT THIS CORRESPONDENCE IS BEING DEPOSITED WITH THE UNITED STATES POSTAL SERVICE AS EXPRESS MAIL IN AN ENVELOPE ADDRESSED TO: COMMISSIONER OF PATENTS AND TRADEMARKS, WASHINGTON, D.C. 20231, NO.: EL086738303US

BY: Robert G. Gsch DATE: August 7, 1998